



3mm One Position SMD CBI Housing

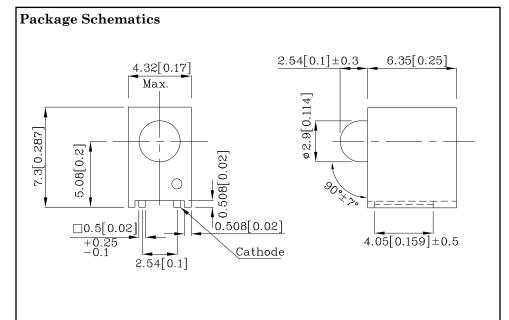
Features

- Black casing provides superior contrast
- Reliable & robust
- Standard Package: 500pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- Housing UL rating:94V-0.
- Housing material: PPA
- High temperature resistant housing.
- High glass transition temperature epoxy.
- RoHS compliant.

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Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

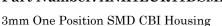
Absolute Maximum Ratings (T _A =25°C)		Red (GaAsP/GaP)	Unit
Reverse Voltage	V_{R}	5	V
Forward Current	I_{F}	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	160	mA
Power Dissipation	P_{D}	75	mW
Operating Temperature	$T_{\rm A}$	-40 ~ +85	$^{\circ}\mathrm{C}$
Storage Temperature	Tstg	-40 ~ +85	

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T _A =25°C)		Red (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V_{F}	1.9	V
Forward Voltage (Max.) (I _F =10mA)	V_{F}	2.5	V
Reverse Current (Max.) $(V_R=5V)$	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λΡ	627*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λD	617*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$\triangle \lambda$	45	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

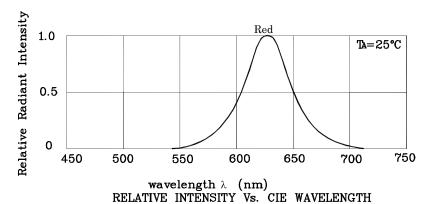
Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} \text{Luminous Intensity} \\ \text{CIE127-2007*} \\ \text{(I}_{\text{F}}\text{=}10\text{mA}) \\ \text{mcd} \end{array}$		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XNK1LUR11DSMD	Red	GaAsP/GaP	Red Diffused	12 10*	29 19*	627*	50°

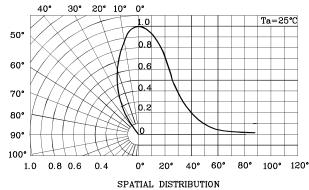
^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



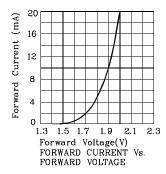


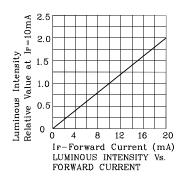


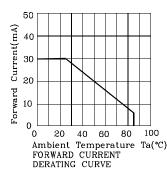


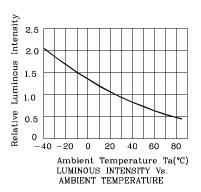


❖ Red

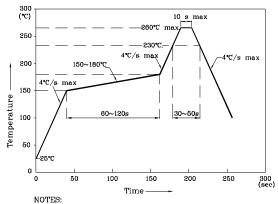








Reflow Soldering Profile for SMD Products (Pb-Free Components)



- 18. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
- 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

3. No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

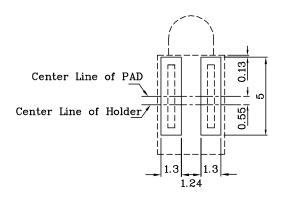
the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

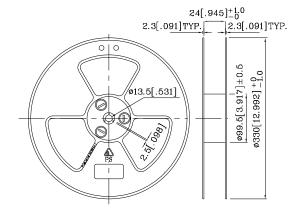
Note: Accuracy may depend on the sorting parameters.



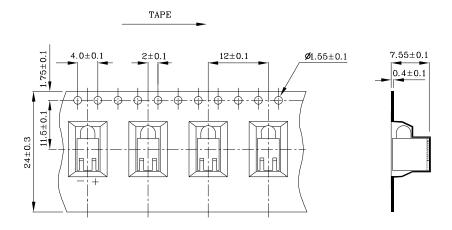
❖ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



❖ Reel Dimension



* Tape Specification (Units:mm)



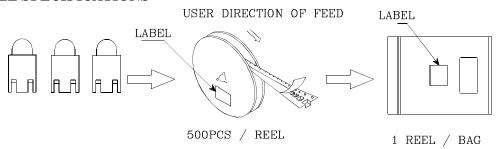
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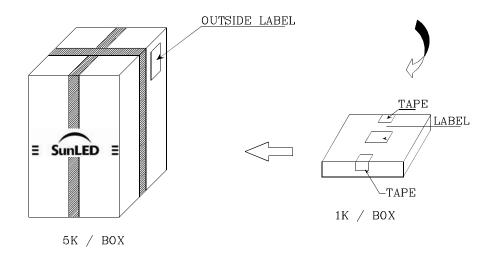


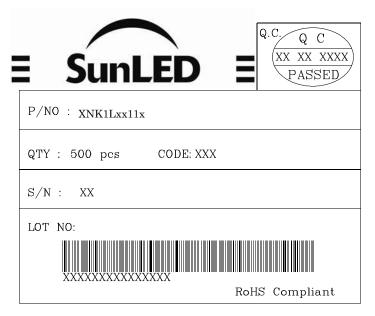


PACKING & LABEL SPECIFICATIONS

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